

# Ultra-Small Diameter Through-Hole

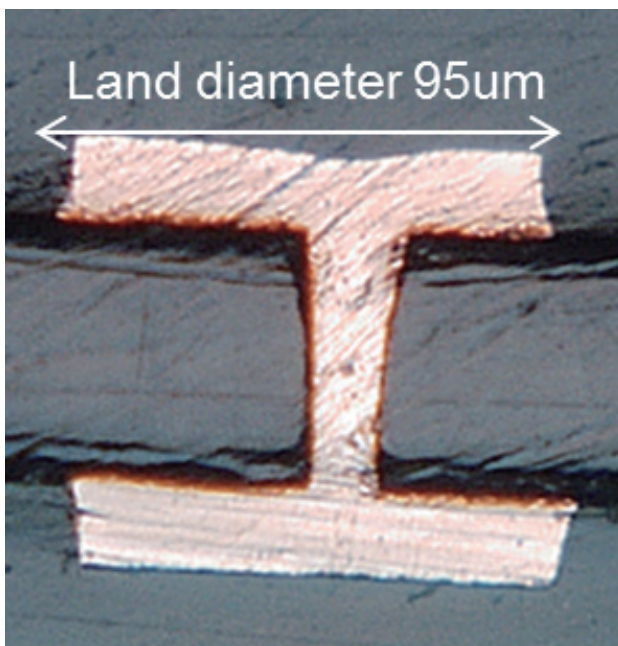
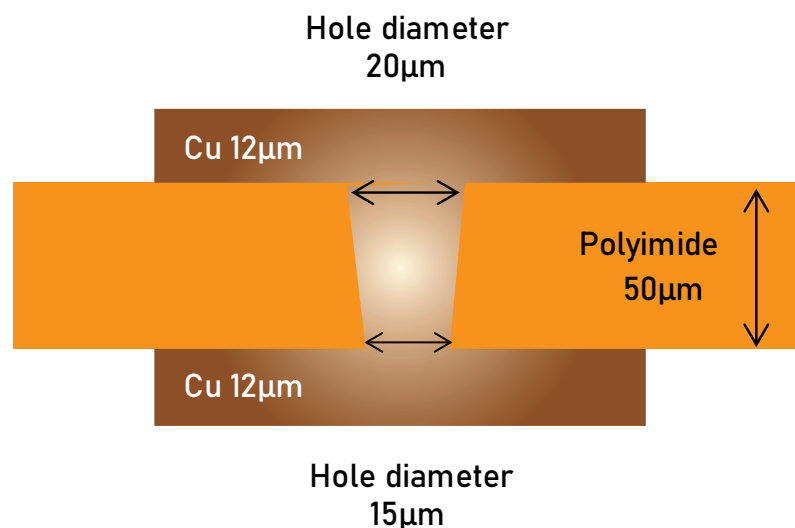
**A through-hole of 25  $\mu\text{m}$  or less in diameter can be formed in double-sided FPC.**

In specifications, a hole is designed to be buried by through-hole plating of 15  $\mu\text{m}$ .

## Specifications

### Standard specifications

Base polyimide	: 50 $\mu\text{m}$
Conductor thickness	: 12 $\mu\text{m}$
Hole diameter (Upper)	: $\phi$ 20 $\mu\text{m}$
Hole diameter (Lower)	: $\phi$ 15 $\mu\text{m}$
Land diameter	: 95 $\mu\text{m}$



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